



REPLY UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2814

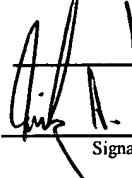
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/777,688  
Filed: February 12, 2004  
Inventor(s):  
Andreas Huschka, Wolfram  
Kluge, and Uwe Hahn

Title: SEMICONDUCTOR DIE  
PACKAGE HAVING TWO  
DIES PADDLES

§ Examiner: Hoai V Pham  
§ Group/Art Unit: 2814  
§ Atty. Dkt. No: 5500-79302  
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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date indicated below.

  
Erik A. Heter  
Printed Name  
Signature  
6/14/06  
Date

RESPONSE TO OFFICE ACTION OF  
April 12, 2006

Box RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This paper is submitted in response to the Office Action of April 12, 2006, to further highlight why the application is in condition for allowance.

Please amend the case as listed below.